

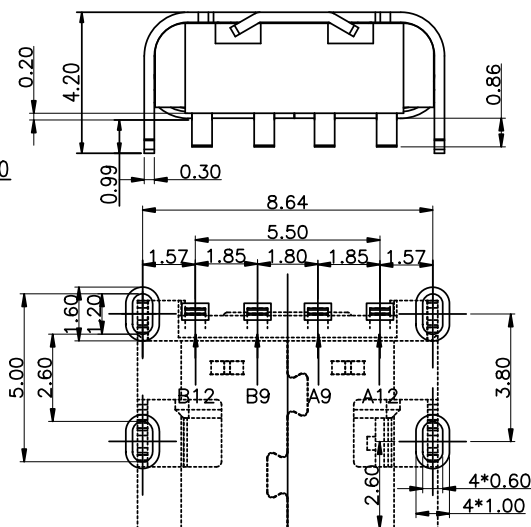
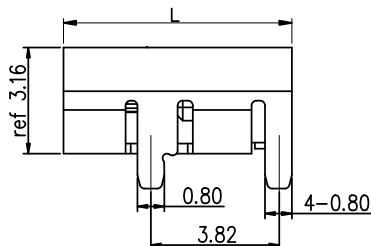
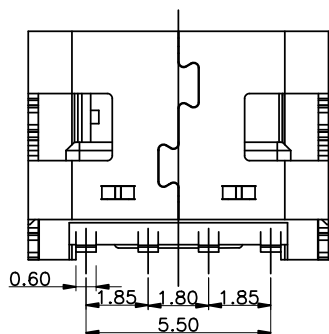
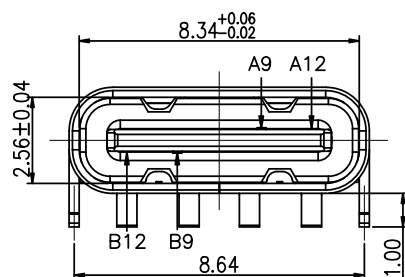
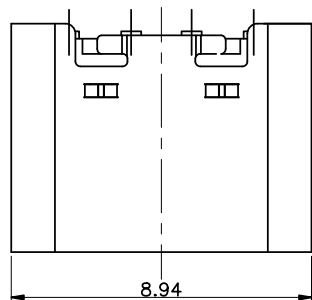
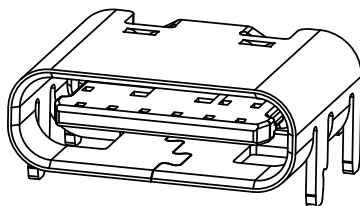
RoHS

MAPX

MODIFICATION

DRW

DATE

RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED ±0.05mm

NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 2.CONTACTS:COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1. CURRENT RATING:3.0A
VOLTAGE RATING:5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40m?/PIN MAX.

SHIELD: 50m?/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10m?.

4-3.INSULATION RESISTANCE: 100M? MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

PIN ASSIGNMENTS

A9	VBUS	B12	GND
A12	GND	B9	VBUS
PIN	SIGNAL NAME	PIN	SIGNAL NAME

产品图

PRODUCT CHART DWG

公差一览表

TOLERANCE UNLESS OTHERWISE

X.	±0.35	X.	±5.°
.X	±0.30	.X	±2.°
.XX	±0.25	.XX	±1.°
.XXX	±0.05	.XXX	±0.5°

深圳市精拓金电子有限公司
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

单位 UNITS	MM	制图 DRAWING	L-S-S	产品料号 PRODUCT PART NO.	918-148M202CE42000
比例 SCALE	1:1	审核 CHKD	G-Z-F	产品名称 PRODUCT NO.	TYPE-C3.1母座板上6.8四脚插板LCP黑胶DIP4PIN
日期 DATE	2021-03-10	核准 APPD	黄国荣	角法 VIEW	版本 VER